

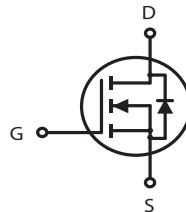


N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
V _{DSS}	I _D	R _{D(S)} (ON) (mΩ) Max
40V	50A	9 @ V _G S = 10V

FEATURES

- Super high dense cell design for low R_{D(S)}(ON).
- Rugged and reliable.
- TO-252 and TO-251 Package.

STU SERIES
TO-252AA(D-PAK)STD SERIES
TO-251(I-PAK)

ABSOLUTE MAXIMUM RATINGS (TC=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	40	V
Gate-Source Voltage	V _G S	±20	V
Drain Current-Continuous ^a @Ta 25°C	I _D	50	A
-Pulsed ^b	I _{DM}	100	A
Drain-Source Diode Forward Current ^a	I _S	20	A
Avalanche Current ^c	I _{AS}	23	A
Avalanche Energy ^c	E _{AS}	130	mJ
Maximum Power Dissipation ^a Ta= 25°C	P _D	50	W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 175	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	R _{θJC}	3	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	50	°C/W

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ELECTRICAL CHARACTERISTICS ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate-Body Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
ON CHARACTERISTICS^a						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	1.25	1.6	3	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 10\text{A}$		7	9	m ohm
		$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 5\text{A}$		9	11	m ohm
On-State Drain Current	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 10\text{V}$	30			A
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 10\text{V}, I_{\text{D}} = 10\text{A}$		28		S
DYNAMIC CHARACTERISTICS^b						
Input Capacitance	C_{ISS}	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$		1130		pF
Output Capacitance	C_{OSS}			240		pF
Reverse Transfer Capacitance	C_{RSS}			145		pF
SWITCHING CHARACTERISTICS^b						
Turn-On Delay Time	$t_{\text{D}(\text{ON})}$	$V_{\text{DD}} = 15\text{V}$ $I_{\text{D}} = 10\text{ A}$ $V_{\text{GS}} = 10\text{V}$ $R_{\text{GEN}} = 3.3\text{ ohm}$		18		ns
Rise Time	t_r			22		ns
Turn-Off Delay Time	$t_{\text{D}(\text{OFF})}$			61		ns
Fall Time	t_f			9.6		ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 15\text{V}, I_{\text{D}} = 10\text{A}, V_{\text{GS}} = 10\text{V}$		23.5		nC
		$V_{\text{DS}} = 15\text{V}, I_{\text{D}} = 10\text{A}, V_{\text{GS}} = 4.5\text{V}$		11.5		nC
Gate-Source Charge	Q_{gs}	$V_{\text{DS}} = 15\text{V}, I_{\text{D}} = 10\text{A}$ $V_{\text{GS}} = 10\text{V}$		2.7		nC
Gate-Drain Charge	Q_{gd}			3.2		nC

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ELECTRICAL CHARACTERISTICS ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS ^a						
Diode Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 20A$		0.91	1.3	V

Notes

- a. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.
- c. Starting $T_J=25^\circ\text{C}$, $L=0.5\text{ mH}$, $R_G=25\Omega$, $I_{AS}=23\text{A}$, $V_{DD}\leq V_{(BR)DSS}$ (See Figure 13)

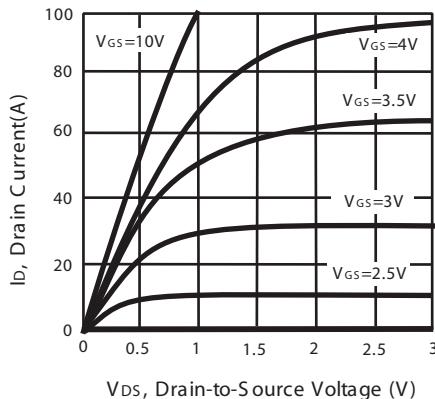


Figure 1. Output Characteristics

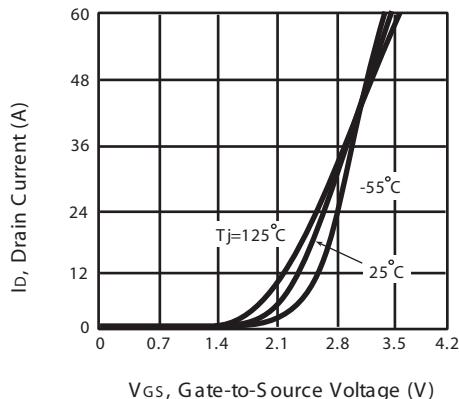


Figure 2. Transfer Characteristics

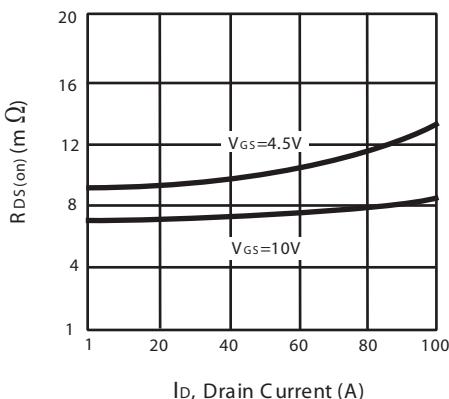


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

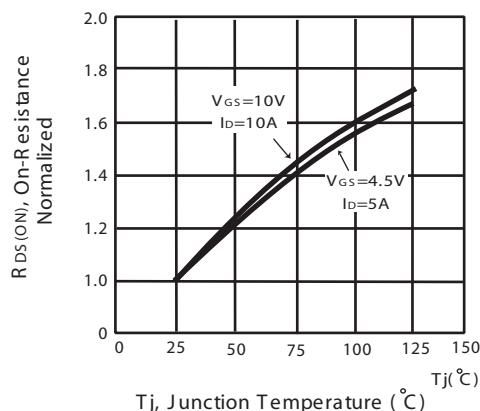


Figure 4. On-Resistance Variation with Drain Current and Temperature

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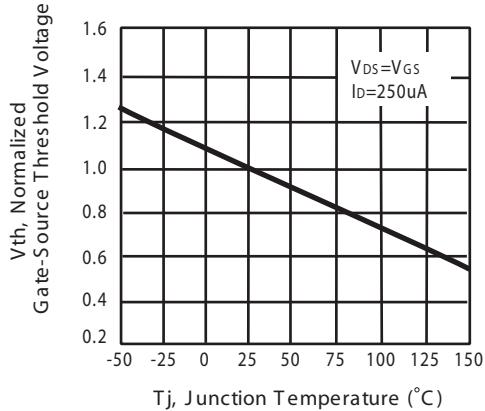


Figure 5. Gate Threshold Variation with Temperature

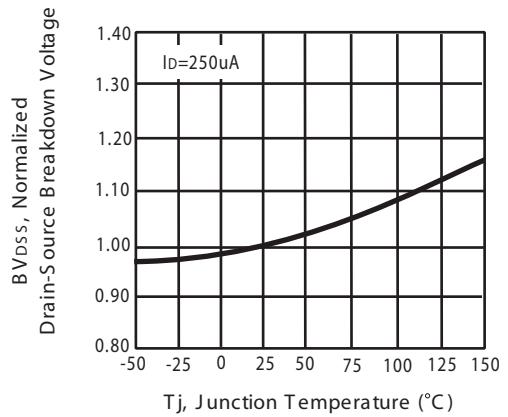


Figure 6. Breakdown Voltage Variation with Temperature

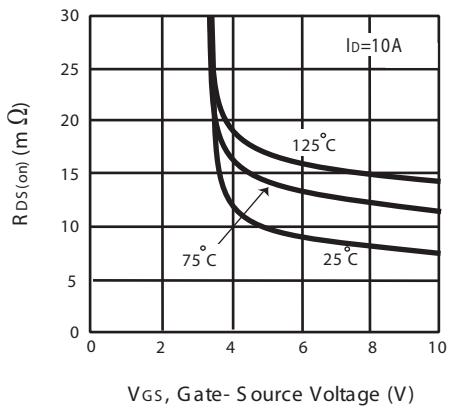


Figure 7. On-Resistance vs. Gate-Source Voltage

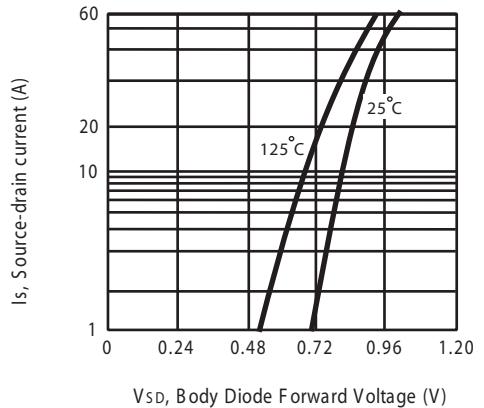


Figure 8. Body Diode Forward Voltage Variation with Source Current

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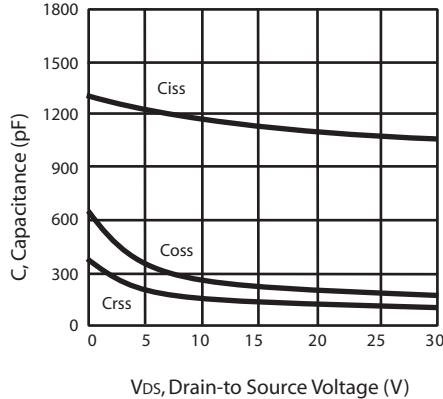


Figure 9. Capacitance

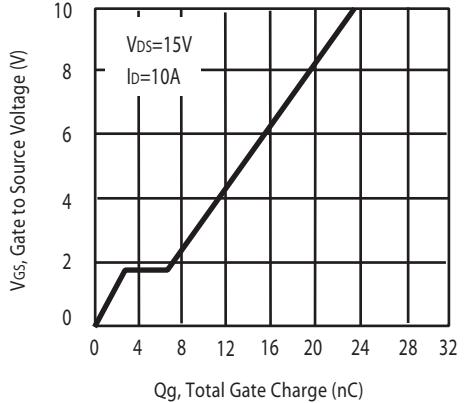


Figure 10. Gate Charge

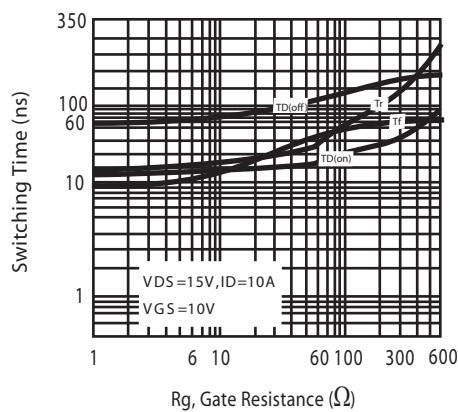


Figure 11. switching characteristics

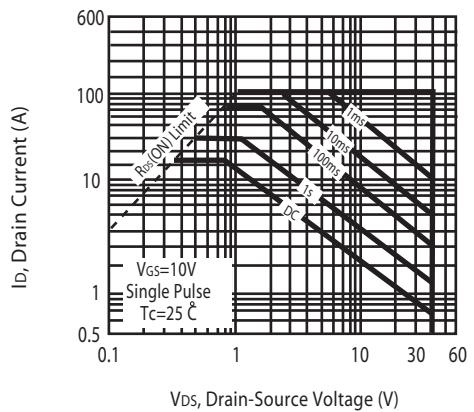
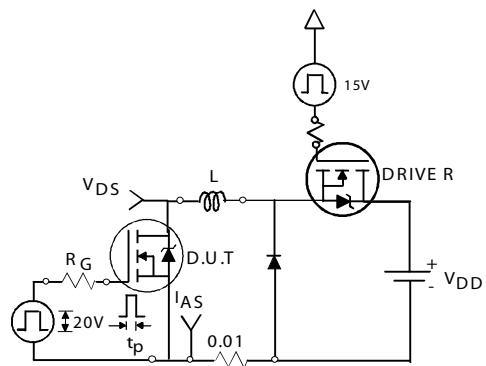


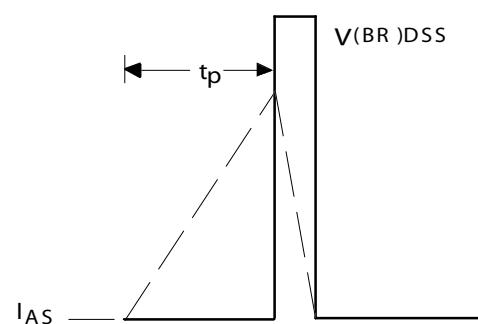
Figure 12. Maximum Safe Operating Area

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Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

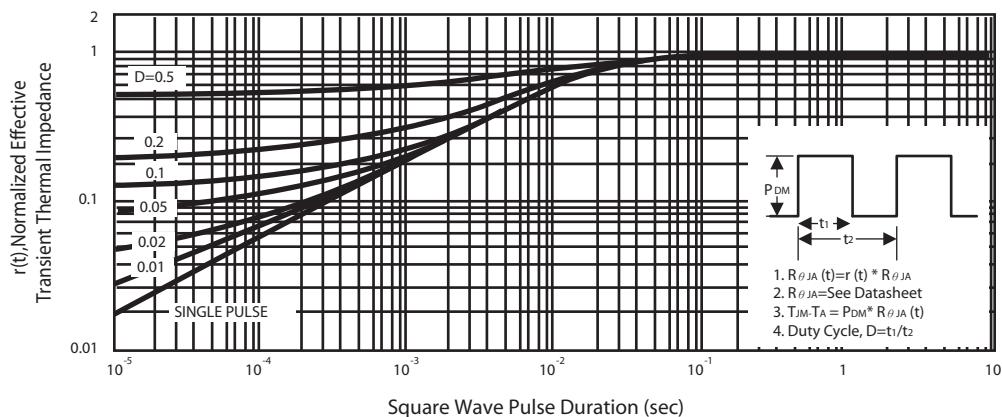
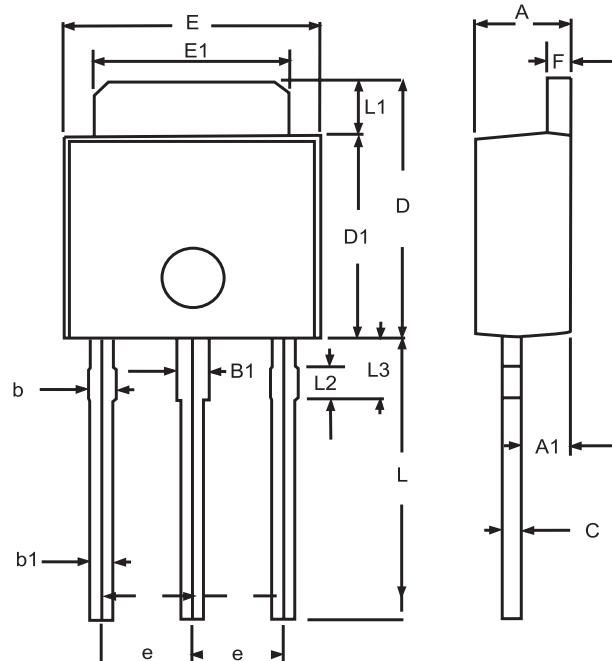


Figure 14. Normalized Thermal Transient Impedance Curve

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PACKAGE OUTLINE DIMENSIONS

TO-251

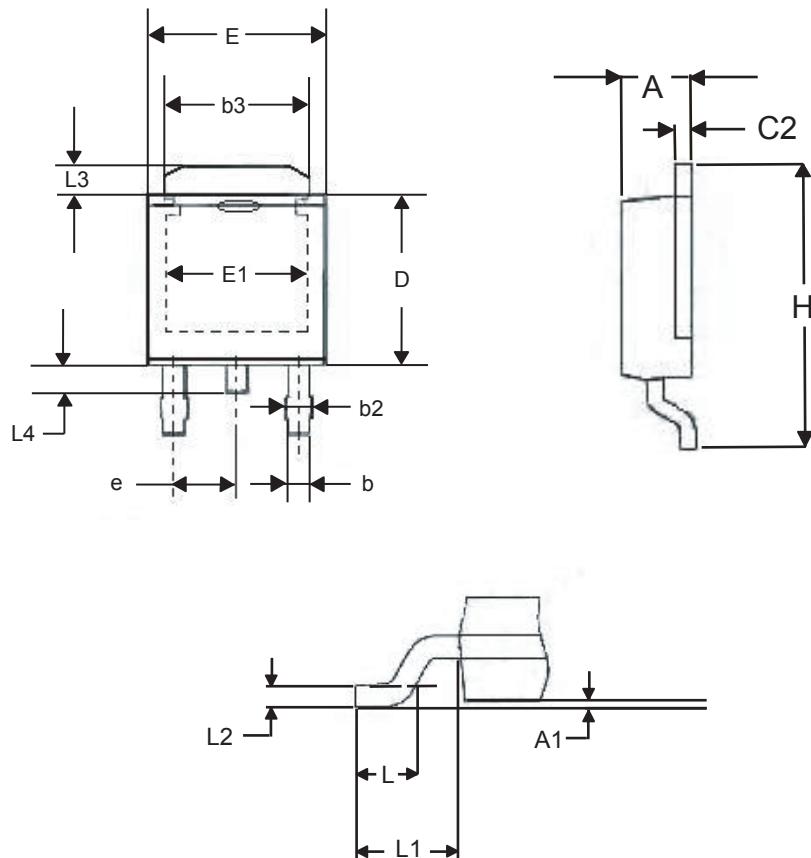


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.20	2.40	0.087	0.095
A1	1.100	1.300	0.043	0.051
B1	0.650	1.050	0.026	0.041
b	0.500	0.900	0.020	0.035
b1	0.400	0.800	0.016	0.32
C	0.400	0.600	0.016	0.024
D	6.700	7.300	0.264	0.287
D1	5.400	5.650	0.213	0.222
E	6.40	6.650	0.252	0.262
e	2.100	2.500	0.083	0.098
F	0.400	0.600	0.016	0.024
L	7.000	8.000	0.276	0.315
L1	1.300	1.700	0.051	0.067
L2	0.700	0.900	0.028	0.035
L3	1.400	1.800	0.055	0.071

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PACKAGE OUTLINE DIMENSIONS

TO-252

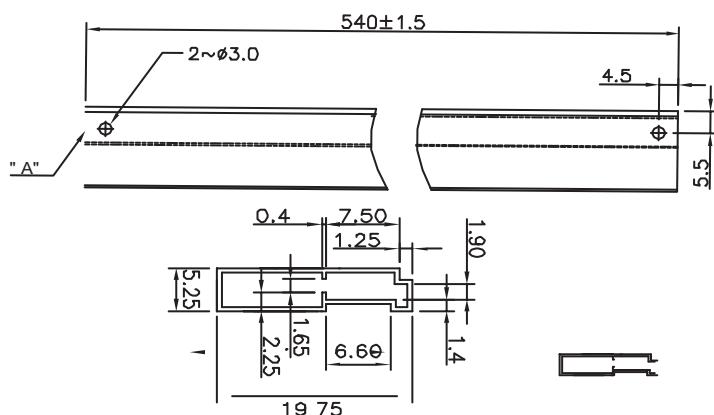


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.210	2.387	0.087	0.094
C2	0.483	0.584	0.019	0.023
b	0.814	0.889	0.032	0.035
b2	0.864	1.092	0.034	0.043
b3	5.232	5.436	0.206	0.214
L2	0.508	REF.	0.020	REF.
D	6.000	6.200	0.236	0.244
E	6.400	6.604	0.252	0.260
E1	4.902	5.004	0.193	0.197
e	2.290	BSC	0.090	BSC
H	9.601	10.210	0.378	0.402
A1	0.010	0.127	0.0004	0.005
L4	0.066	0.940	0.026	0.037
L	1.397	1.651	0.055	0.065
L1	2.743	REF.	0.108	REF.
L3	1.100	REF.	0.043	REF.

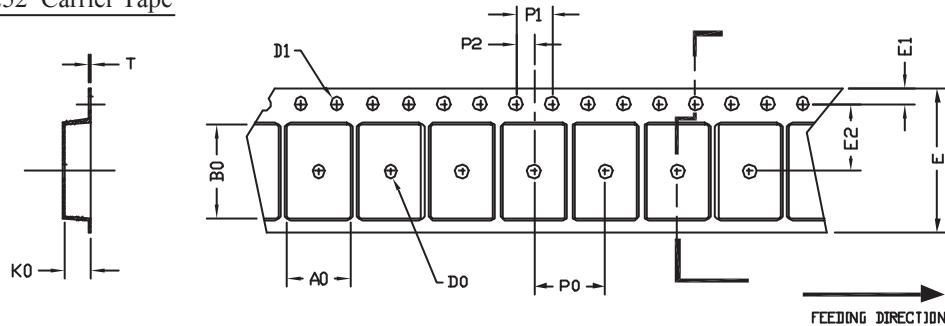
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TO251 Tube/TO-252 Tape and Reel Data

TO-251 Tube



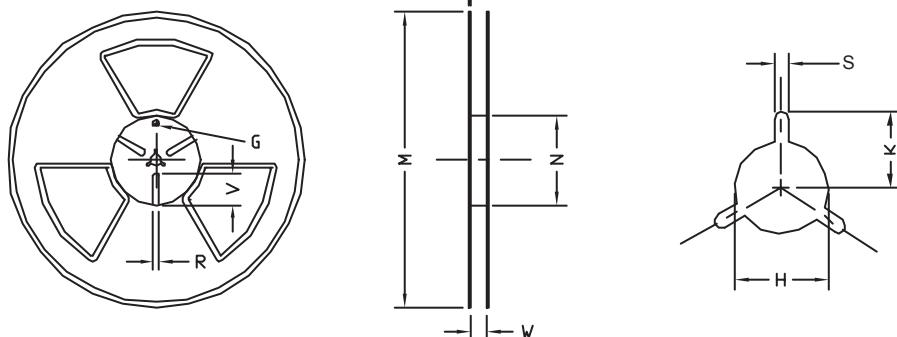
TO-252 Carrier Tape



UNIT:mm

PACKAGE	A_0	B_0	K_0	D_0	D_1	E	E_1	E_2	P_0	P_1	P_2	T
TO-252 (16 mm)	6.80 ± 0.1	10.3 ± 0.1	2.50 ± 0.1	$\phi 2$	$\phi 1.5$ $+ 0.1$ $- 0$	16.0 $0.3 \pm$	1.75 $0.1 \pm$	7.5 ± 0.15	8.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.15	0.3 ± 0.05

TO-252 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	T	H	K	S	G	R	V
16 mm	$\phi 330$	$\phi 330$ ± 0.5	$\phi 97$ ± 1.0	17.0 $+ 1.5$ $- 0$	2.2	$\phi 13.0$ $+ 0.5$ $- 0.2$	10.6	2.0 ± 0.5	---	---	---